

METALLIC SPUTTERING TARGET, PRODUCTION METHOD THEREFOR, AND METALLIC MATERIAL AND PRODUCTION METHOD THEREFOR

ABSTRACT

Provided is at least one of a metal material including a metal having a body-centered cubic structure, the metal material being suitable as a sputtering target, a method for producing the metal material, a sputtering target including the metal material, and a method for producing a film, the method including using the sputtering target.

A metal material includes a metal having a body-centered cubic structure, in which with respect to a sum of orientation area fractions of a $\{001\}$ plane, a $\{101\}$ plane and a $\{111\}$ plane, a ratio of the orientation area fraction of the $\{111\}$ plane is 0.45 or more.

[Fig. 1]